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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Patent Application of

EAC

Atty. Ref.: 4209-29

Serial No. 10/815,992

Group: 3753

Filed: April 2, 2004

Examiner:

For: DIFFUSION BONDED WIRE MESH HEAT SINK

\* \* \* \* \*

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**INFORMATION DISCLOSURE STATEMENT**

As suggested by 37 C.F.R. 1.97, the undersigned attorney brings to the attention of the Patent and Trademark Office the references listed on the attached form PTO-1449.

☐ All listed documents are attached.

☒ This application was filed after June 30, 2003 so that copies of U.S. Patent Publications are not required and are not attached.

☒ Listed foreign patent publications and other documents are enclosed.

☐ The partial translations were provided to the undersigned by the applicants' foreign representative. The undersigned has no knowledge regarding the pertinency of the partially translated portions vis-à-vis the document as a whole. The partial translations are merely provided for whatever convenience they may be.

☐ The listed documents were cited in the ISR and copies should have been supplied by WIPO directly to the US PTO. If copies are not timely received from WIPO, please telephone the undersigned so that copies can be timely supplied for the Examiner's consideration in this US National Phase Application.

This is not to be construed as a representation that a search has been made or that no better prior art exists, or that a reference is relevant merely because cited.

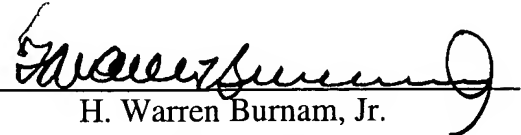
EAST  
Serial No. 10/815,992

The Examiner is requested to initial the attached form PTO-1449 and to return a copy of the initialed document to the undersigned as an indication that the attached references have been considered and made of record.

Respectfully submitted,  
NIXON & VANDERHYE P.C.

July 22, 2004

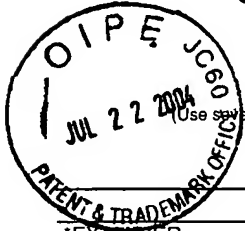
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**INFORMATION DISCLOSURE  
CITATION**

ATTY. DOCKET NO.

SERIAL NO.

4209-29

10/815,992

APPLICANT

EAST

FILING DATE

GROUP

April 2, 2004

3753

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	2002/0108743	8-2002	Wirtz			
	4,880,052	11-1989	Meyer, IV et al.			
	4,577,398	3-1986	Sliwa et al.			
	5,688,716	11-1997	DiStefano et al.			
	5,583,317	12-1996	Mennucci et al.			
	5,777,259	7-1998	Mennucci et al.			
	5,987,893	11-1999	Schulz-Harder et al.			
	6,014,312	1-2000	Schulz-Harder et al.			
	6,317,326	11-2001	Vogel et al.			
	4,717,433	1-1988	Weisert et al.			
	5,325,913	7-1994	Altoz			
	5,526,867	6-1996	Keck et al.			

**FOREIGN PATENT DOCUMENTS**

DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO

**OTHER DOCUMENTS (including Author, Title, Date, Pertinent pages, etc.)**

	Zheng et al, "Cylindrical Pin-Fin Fan-Sink Heat Transfer and Pressure Drop Correlations", IEEE Trans. Components and Packaging Technology, vol. 25, also ASME/JSME Thermal Engineering Joint Conference Proceedings, paper AJTE99-6197, 1999,
	Wirtz, "High Performance Woven Mesh Heat Exchange", F49620-99-1-0286, 1999
	"High Performance Woven Mesh Heat Exchange", Research Summary, AFOSR Contractors' Meeting in Turbulence and Rotation Flows, Albuquerque, NM, August 18-19, 1999
	Xu et al, "In-Plane Effective Thermal Conductivity of Plain Weave Screen Laminates with Arbitrary Weave Parameters", Paper TED-AJ03-417, 6 <sup>th</sup> ASME/JSME Thermal Engineering Joint Conference, Hawaii, March 16-20, 2003
	Xu et al, "In-Plane Effective Thermal Conductivity of Plain-Weave Screen Laminates", IEEE Trans. on Components and Packaging Tech., vol. 25, #4, 2003. See also Proc. THERMES 2002, pp. 231-242, Millpress, Rotterdam, January 2002
	Wirtz et al, "Thermal/Fluid Characteristics of 3-D Woven Mesh Structures as Heat Exchanger Surfaces", IEEE Trans Components and Packaging Technology, vol. 26, 2003, pp.40-47. See also paper 1372, Eighth Intersociety Conference on Thermal Phenomena in Electronic Systems", San Diego, CA
	Li et al, "Development of a High-Performance Heat Sink Based on Screen-Fin Technology", Proc 19-th Semiconductor Thermal Measurement and Management Symposium, IEEE 02CH37437, March 6-10, 2003, pp. 53-60

*Examiner	Date Considered
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Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application.

Form PTO-FB-A820 (Also PTO-1449)